

REMARKS

Applicants have amended their claims in order to further clarify the definition of the present invention. Specifically, claims 2 and 3 have been made to be dependent claims, dependent on claim 1. Furthermore, claim 1 has been amended to recite that the adhesive includes a first adhesive layer which includes an adhesive resin composition and an insulative inorganic filler. Claim 3 has been further amended to recite that the adhesive further includes the second adhesive layer containing an adhesive resin composition "as a main ingredient".

Moreover, Applicants have added new claim 32 to the application. Claim 32, depended on claim 1, recites that the adhesive consists of the first adhesive layer.

The restriction requirement as set forth in Item 1 on page two of the Office Action mailed February 20, 2002, is noted. Applicants respectfully elect the Group I claims, directed to an adhesive. In so far as the claims are presently amended, it is respectfully submitted that claims 1-21 (including claim 2) and newly added claim 32 read on the elected Group I claims.

Insofar as claim 2 is incorporated within Group I claims, Applicants make the present election of the Group I claims without traverse. However, if the Examiner maintains claim 2 as part of the Group II claims, Applicants respectfully traverse the restriction requirement, and respectfully submit that claim 2, which defines an

adhesive for bonding circuit members according to claim 1, should be part of the Group I claims.

The election-of-species requirement as set forth in Items 5 and 6 on page 3 of the Office Action mailed February 20, 2002 is noted. Applicants respectfully elect the Species A defined by adhesive one recited on page 3 of Applicants' specification. It is respectfully submitted that, in view of the presently amended claims, claims 1-3 and 14-21 read on the elected species.

In view of all of the foregoing, consideration of the Group I claims, and the Species A claims within the Group I claims, that is, claims 1-3 and 14-21, in due course, on the merits of the present application, is respectfully requested.

Attached hereto is a marked-up version of the changes made to the claims by the current Amendment. The changes are on the attached pages, the first page of which is captioned "VERSION WITH MARKINGS TO SHOW CHANGES MADE".

Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to the Deposit Account No. 01-2135 (Case No. 566.39636X00) and please credit any excess fees to such Deposit Account.

Respectfully submitted,

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**VERSION WITH MARKINGS TO SHOW CHANGES MADE-PAGE 1**

1. (Twice Amended) An adhesive for bonding circuit members which is to be put between circuit electrodes facing each other;

said circuit electrodes facing each other being pressed interposing the adhesive between them, to interconnect the electrodes electrically in the direction of pressing;

said adhesive comprising a first adhesive layer which includes an adhesive resin composition and an insulative inorganic filler;

said insulative inorganic filler being contained in an amount of from 10 to 200 parts by weight based on 100 parts by weight of the adhesive resin composition.

2. (Twice Amended) An adhesive for bonding circuit members according to claim 1, [which is to be put between circuit electrodes facing each other;

said circuit electrodes facing each other being pressed interposing the adhesive between them, to interconnect the electrodes electrically in the direction of pressing;

said adhesive being in multi-layer constitution having;

a first adhesive layer comprising an adhesive resin composition and an insulative inorganic filler and containing the insulative inorganic filler in an amount of from 10 to 200 parts by weight based on 100 parts by weight of the adhesive resin composition; and] said adhesive further comprising a second adhesive layer containing an adhesive resin composition as a main ingredient.

**VERSION WITH MARKINGS TO SHOW CHANGES MADE-PAGE 2**

3. (Twice Amended) An adhesive for bonding circuit members according to claim 1, [which is to be put between circuit electrodes facing each other; said circuit electrodes facing each other being pressed interposing the adhesive between them, to interconnect the electrodes electrically in the direction of pressing;

said adhesive being in multi-layer constitution having;

a first adhesive layer comprising an adhesive resin composition and an insulative inorganic filler and containing the insulative inorganic filler in an amount of from 10 to 200 parts by weight based on 100 parts by weight of the adhesive resin composition; and] said adhesive further comprising a second adhesive layer containing an adhesive resin composition as a main ingredient and having a modulus of elasticity of from 100 to 2,000 MPa at 40°C after curing.